



L Number	Hits	Search Text	DB	Time stamp
1	760	capillary and wire and bond\$ and coin\$ and @ad<20010104	USPAT;	2003/09/17 17:07
	`		US-PGPUB;	
			EPO; JPO;	
l			DERWENT;	
			IBM_TDB	
2 •	252	(capillary and wire and bond\$ and coin\$ and @ad<20010104) and	USPAT;	2003/09/17 16:40
		semiconductor	US-PGPUB;	
			EPO; JPO;	
	!		DERWENT;	
			IBM_TDB	,
3	162	((capillary and wire and bond\$ and coin\$ and @ad<20010104) and	USPAT;	2003/09/17 16:41
		semiconductor) and coat\$	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
}	29	((capillary and wire and bond\$ and coin\$ and @ad<20010104) and	USPAT;	2003/09/17 16:41
	•	semiconductor) and (coat\$ near4 wire)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
;	92	capillary and wire and bond\$ and (coin coined coining) and	USPAT;	2003/09/17 17:08
		@ad<20010104	US-PGPUB;	
		O	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
;	41	(capillary and wire and bond\$ and (coin coined coining) and	USPAT;	2003/09/17 17:24
´	••	@ad<20010104) and semiconductor	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
7	516	(wave adj solder\$4) and @ad<20010104 and semiconductor	USPAT;	2003/09/17 17:25
	310	(National Solution) and Country and Dollars and Dollars	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
	65	((wave adj solder\$4) and @ad<20010104 and semiconductor) and core	USPAT;	2003/09/17 17:25
·	05	((Wave adj Solders) and wad 2001010 1 and someone and some	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	56	(((wave adj solder\$4) and @ad<20010104 and semiconductor) and core)	USPAT;	2003/09/17 17:25
)	50	and bond\$4	US-PGPUB;	
		and bondyt	EPO; JPO;	
		·	DERWENT;	
			IBM_TDB	
	79	ibm.as. and (flip adj chip) and @ad<20010104	USPAT;	2003/09/17 16:38
	19	ioni.as. and (mp adj emp) and wad 20010104	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	700	(Air - 4; ship) and God < 20010104 and colder and core	USPAT;	2003/09/17 11:35
-	798	(flip adj chip) and @ad<20010104 and solder and core	US-PGPUB;	2003/07/17 11.55
			EPO; JPO;	
			DERWENT;	
-		(/0: 1: 1:) 0 - 1 < 0.010104 - 1.1 - 1	IBM_TDB	2003/09/17 13:4
	286	((flip adj chip) and @ad<20010104 and solder and core) and (dip\$4	USPAT;	2003/09/1/13:4
		wave)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	L

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•	917	(solder near4 wave) and @ad<20010104 and (semiconductor ic chip	USPAT;	2003/09/17 13:48
		(integrated adj circuit))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	112	((solder near4 wave) and @ad<20010104 and (semiconductor ic chip	USPAT;	2003/09/17 14:11
		(integrated adj circuit))) and core	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	701	(solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and core	USPAT;	2003/09/17 14:14
		and (bump ball)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	179	(solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and	USPAT;	2003/09/17 14:14
		(solder near4 core) and (bump ball)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	137	((solder near4 (molten melt\$3 liquid dip\$4)) and @ad<20010104 and	USPAT;	2003/09/17 14:15
		(solder near4 core) and (bump ball)) and (semiconductor IC (integrated	US-PGPUB;	
		adj circuit) chip die)	EPO; JPO;	
			DERWENT;	
			IBM TDB	